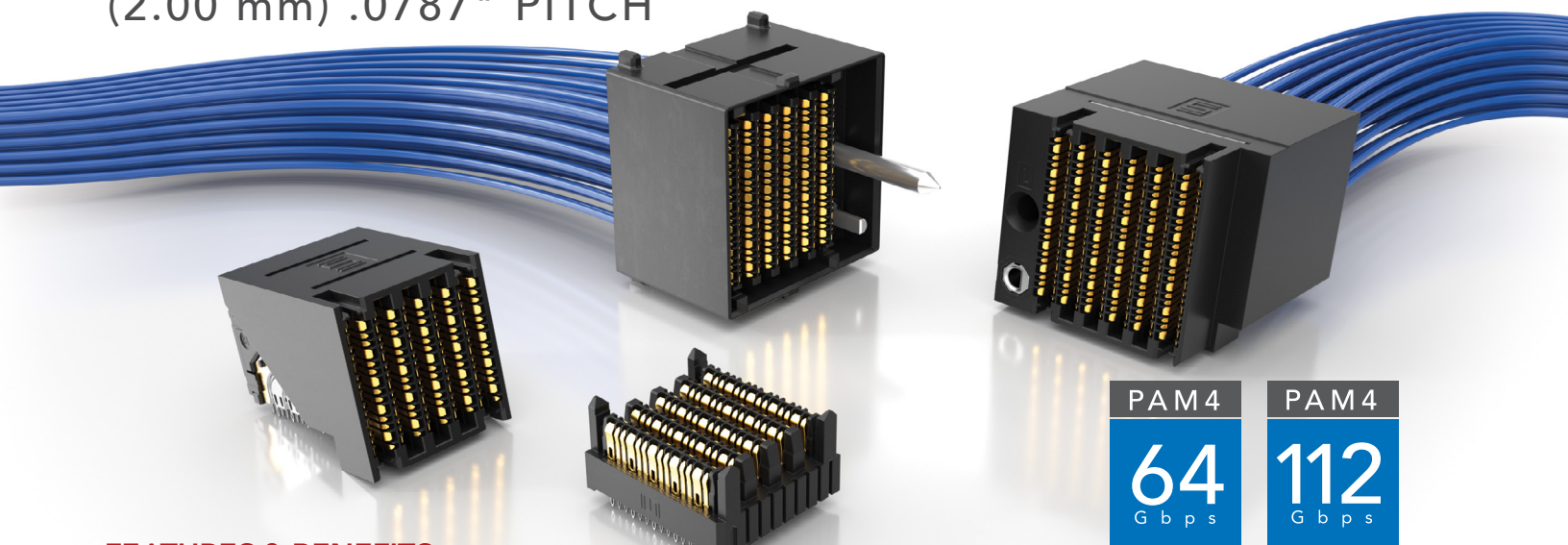


ExaMAX[®]

HIGH-SPEED BACKPLANE CONNECTOR & CABLE SYSTEMS

(2.00 mm) .0787" PITCH



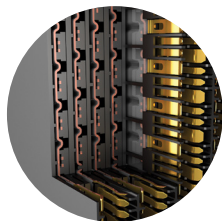
FEATURES & BENEFITS

ExaMAX[®] High-Speed Backplane System

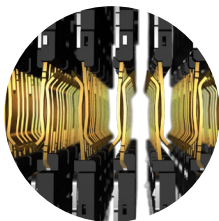
- Meets a variety of industry specifications
- Traditional, coplanar and direct mate orthogonal
- 24 - 72 pair designs (4 and 6 pairs; 6, 8, 10 and 12 columns)
- Shielded wafer design reduces crosstalk and includes one sideband signal per column
- Press-fit tails provide a reliable electrical connection
- PCIe[®] 6.0/CXL[®] 3.2 capable

ExaMAX[®] High-Speed Backplane Cable Assemblies

- 30 & 34 AWG Eye Speed[®] ultra low skew twinax cable
- 34 AWG Eye Speed Thinax[™] ultra low skew twinax cable
- Offers improved signal integrity, increased flexibility and routability
- Highly customizable with modular flexibility
- Reduce costs due to lower layer counts
- PCIe[®] 6.0/CXL[®] 3.2 capable



Staggered
Differential
Pair Design



Two Reliable Points
of Contact with
a 2.4 mm Wipe



In Development:
Open-Pin-Field,
Coplanar Configuration



In Development:
2 Pair Design for
a Lower Profile



In Development:
ExaMAX2[®] 8 Pairs
for 112 Gbps PAM4
Performance

KEY SPECIFICATIONS

SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
EBTM/EBTF/EBDM	Liquid Crystal Polymer	Copper Alloy	Sn or Au over 50 μ" (1.27 μm) Ni	-55 °C to +105 °C	4 A per pin	150 VAC/212 VDC	Yes
EPTT/EPTS	High Temperature Thermoplastic	Copper Alloy	Sn or Au over 50 μ" (1.27 μm) Ni	-55 °C to +105 °C	14.1 A per pin	150 VAC/212 VDC	Yes
EBCM/EBCF	Liquid Crystal Polymer	Copper Alloy	Au over 50 μ" (1.27 μm) Ni	-40 °C to +105 °C	2.6 A per pin	125 VAC/177 VDC	N/A

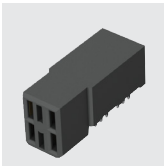
PCI-SIG[®], PCI Express[®] and the PCIe[®] design marks are registered trademarks and/or service marks of PCI-SIG.

ExaMAX[®] POWER MODULES

(2.00 mm) .0787" PITCH TERMINAL POWER MODULES

	EPTT Mates with: EPTS	EPTT	POSITIONS PER ROW	PLATING	HEIGHT	D	ORIENTATION
			-2 = 4 Positions	-P = Palladium with flash Gold on contacts, Matte Tin on tails	-11.5 = (11.50 mm) .453"		-RA = Right-Angle

(2.00 mm) .0787" PITCH SOCKET POWER MODULES

	EPTS Mates with: EPTT	EPTS	POSITIONS PER ROW	PLATING	D	ORIENTATION	PIN STAGING
			-2 = 4 Positions	-P = Palladium with flash Gold on contacts, Matte Tin on tails		-VT = Vertical -RA = Right-Angle	Visit website for dimensions. -01 thru -06 (Vertical) -04 & -08 (Right-Angle)

View complete specifications at: samtec.com?EPTT & samtec.com?EPTS

ExaMAX[®] GUIDE MODULES

TERMINAL GUIDE MODULES

	EGBM Mates with: EGBF Insulator Material: Zinc Alloy	EGBM	ORIENTATION	THREADING	LENGTH	CARD SPACING
			-VT = Vertical -RA = Right-Angle	Leave Blank for -RA -1 = External -2 = Internal (25.3 Length only)	Leave Blank for -RA -18.3 = 18.30 mm (.720") -25.3 = 25.30 mm (.996")	-20 = 20 mm (.787")

SOCKET GUIDE MODULES

	EGBF Mates with: EGBM Insulator Material: Zinc Alloy	EGBF	ORIENTATION	CARD SPACING
			-RA = Right-Angle	-20 = 20 mm (.787")

Notes:
Some lengths, styles and options are non-standard, non-returnable.

ExaMAX[®] is a registered trademark of AFCL.

View complete specifications at: samtec.com?EGBM & samtec.com?EGBF